

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10680509			
<b>Filing Date:</b>	07-Oct-2003			
<b>Title of Invention:</b>	ADHESIVE BONDING WITH LOW TEMPERATURE GROWN AMORPHOUS OR POLYCRYSTALLINE COMPOUND SEMICONDUCTORS			
<b>First Named Inventor/Applicant Name:</b>	Kuang Chien Hsieh			
<b>Filer:</b>	Mindy Niedzielka Rittner/Corinne Roempagel			
<b>Attorney Docket Number:</b>	10322/57			
Filed as Small Entity				
<b>Utility</b>	<b>Filing Fees</b>			
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	2501	1	720	720
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				720